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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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## Metal Composite Power Inductor (Thin Film) Specification Sheet



#### CIGT201608LMR24MNE (2016 / EIA 0806)

#### APPLICATION

Smart phones, Tablet, Wearable devices, Power converter modules, etc.

#### **FEATURES**

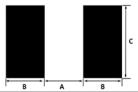
Small power inductor for mobile devices
Low DCR structure and high efficiency inductor for power circuits.
Monolithic structure for high reliability
Free of all RoHS-regulated substances
Halogen free

#### DIMENSION





RECOMMENDED	LAND PATTERN
	1



Unit : mm
2016
0.8
0.8
1.8

TYPE	Dimension [mm]						
ITFE	L	W	T	D			
2016	2.0±0.2	1.6±0.2	0.8 max	0.5±0.2			

#### DESCRIPTION

Part no.	Size	Thickness	Inductance	Inductance tolerance (%)	DC Resist	ance [mΩ]	Rated DC Cu	rrent (Isat) [A]	Rated DC Cu	rrent (Irms) [A]
T art no.	[inch/mm]	[mm] (max)	[uH]		Max.	Тур.	Max.	Тур.	Max.	Тур.
CIGT201608LMR24MNE	0806/2016	0.8	0.24	±20	23	21	4.3	4.7	3.6	4

- \* Inductance : Measured with a LCR meter 4991A(Agilent) or equivalent (Test Freq. 1MHz, Level 0.1V)
- \* DC Resistance : Measured with a Resistance HI-TESTER 3541(HIOKI) or equivalent
- \* Maximum allowable DC current: Value defined when DC current flows and the initial value of inductance has decreased by 30% or

when current flows and temperature has risen to 40°C whichever is smaller. (Reference: ambient temperature is 25°C  $\pm$ 10)

(Isat): Allowable current in DC saturation: The DC saturation allowable current value is specified when the decrease of

the initial inductance value at 30% (Reference: ambient temperature is 25°C±10)

(Irms): Allowable current of temperature rise: The temperature rise allowable current value is specified when temperature of

the inductor is raised 40°C by DC current. (Reference: ambient temperature is 25°C±10)

- \* Absolute maximum voltage : Absolute maximum voltage DC 20V.
- \* Operating temperature range : -40 to +125°C (Including self-temperature rise)

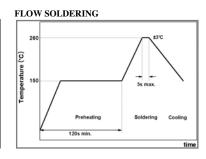
#### PRODUCT IDENTIFICATION

<u>CIG</u>	<u>T</u>	<u> 2016</u>	<u>80</u>	<u>LM</u>	<b>R24</b>	M	<u>N</u>	<u>E</u>
(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)

- (1) Power Inductor
- (3) Dimension (2016: 2.0mm ×1.6 mm)
- (5) Remark (Characterization Code)
- (7) Toleranc (M:±20%)
- (8) Internal Code
- (9) Packaging (C:paper tape, E:embossed tape)
- (2) Type (T: Metal Composite Thin Film Type)
- (4) Thicknes (08: 0.8mm)
- (6) Inductan (R24: 0.24 uH)

#### RECOMMENDED SOLDERING CONDITION

# REFLOW SOLDERING 280 230 180 180 Preheating Soldering Cooling 30 - 60s max. 60 - 120s



IRON SOLDERING	
Temperature of	280°C max.
Soldering Iron Tip	280 C max.
Preheating	150 ℃ min.
Temperature	130 C min.
Temperature	ΔT≤130℃
Differential	$\Delta 1 \ge 130 \text{ C}$
Soldering Time	3sec max.
Soldering Time	JSCC IIIax.
Wattage	50W max

#### PACKAGING

Packaging Style	Quantity(pcs/reel)
Embossed Taping	3000 pcs

Item	Specified Value	Test Condition			
Solderability	More than 90% of terminal electrode should be soldered newly.	After being dipped in flux for $4\pm1$ seconds, and preheated at $150\sim180^{\circ}\!$			
Resistance to Soldering	No mechanical damage. Remaining terminal Electrode: 75% min. Inductance change to be within ±20% to the initial.	After being dipped in flux for 4 $\pm$ 1 seconds, and preheated at 150 $\sim$ 180 $^{\circ}$ C for 2 $\sim$ 3 min, the specimen shall be immersed in solder at 260 $\pm$ 5 $^{\circ}$ C for 10 $\pm$ 0.5 seconds.			
Thermal Shock (Temperature Cycle test)	No mechanical damage Inductance change to be within ±20% to the initial.	Repeat 100 cycles under the following conditions40 $\pm$ 3 °C for 30 min $\rightarrow$ 85 $\pm$ 3 °C for 30 min			
High Temp. Humidity Resistance Test	No mechanical damage Inductance change to be within ±20% to the initial	85±2°C, 85%RH, for 500±12 hours. Measure the test items after leaving at normal temperature humidity for 24 hours.	and		
Low Temperature Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Exposure at -55±2°C for 500±12 hours.  Measure the test items after leaving at normal temperature humidity for 24hours.	and		
High Temperature Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Exposure at 125±2°C for 500±1 hours.  Measure the test items after leaving at normal temperature humidity for 24hours.			
High Temp. Humidity Resistance Loading Test	No mechanical damage Inductance change to be within ±20% to the initial	85±2°C, 85%RH, Rated Current for 500±12 hours. Measure the test items after leaving at normal temperature humidity for 24 hours.	and		
High Temperature Loading Test	No mechanical damage Inductance change to be within ±20% to the initial	85±2°C, Rated Current for 500±12 hours.  Measure the test items after leaving at normal temperature and humidity for 24 hours.			
Reflow Test	No mechanical damage Inductance change to be within ±20% to the initial	Peak 260±5 ℃, 3 times			
Vibration Test	No mechanical damage Inductance change to be within ±20% to the initial.	Solder the sample on PCB. Vibrate as apply 10~55Hz, 1.5r amplitude for 2 hours in each of three(X,Y,Z) axis (total 6 hours)			
	No mechanical damage	Bending Limit; 2mm Test Speed; 1.0mm/sec. Keep the test board at the limit point in 5 sec. PCB thickness: 1.6mm			
Bending Test	10,	20 Unit :mm  R340  46			
	No indication of peeling shall occur on the	W(kgf) TIME(sec)			
	terminal electrode.	0.5 10±1			
Terminal Adhesion Test		77772 W			
Drop Test	No mechanical damage Inductance change to be within ±20% to the initial.	Random Free Fall test on concrete plate. 1 meter, 10 drops			



## Metal Composite Power Inductor (Thin Film) Data Sheet



#### 1. Model: CIGT201608LMR24MNE

#### 2. Description

Part no.	Size	Thickness	Inductance	Inductance tolerance (%)	DC Resist	ance [mΩ]	Rated DC Cu	rrent (Isat) [A]	Rated DC Cu	rrent (Irms) [A]
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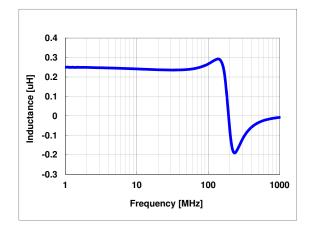
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- \* Absolute maximum voltage : Absolute maximum voltage DC 20V.
- \* Operating temperature range : -40 to +125°C (Including self-temperature rise)

#### 3. Characteristics data

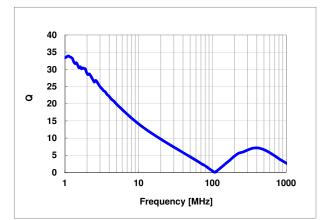
#### 1) Frequency characteristics (Ls)

Agilent E4294A +E4991A , 1MHz to 1,000MHz

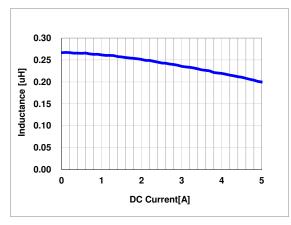


#### 2) Frequency characteristics (Q)

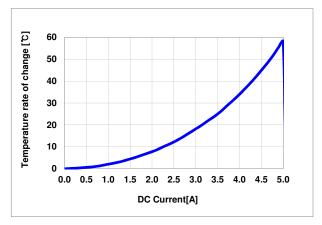
Agilent E4294A +E4991A , 1MHz to 1,000MHz



#### 3) DC Bias characteristics (Typ.)



#### 4)Temperature characteristics (Typ.)





Any data in this sheet are subject to change, modify or discontinue without notice The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers